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MIL-PRF-55110
 MIL-PRF-31032

◆ **PCB Design** ◆ **Fabrication & Assembly** ◆ **Membrane Switches & Overlays**
 ◆ **Sheet Metal & Injection Molding** ◆ **Laser Cut SMT Stencils**

PNC's Technology Roadmap

PNC's technology road map is a guide to enable us to schedule planned improvement in our current capabilities to serve our customer better. It also helps us to fulfill our commitment to ISO9001:2008 requirement of continuous improvement to achieve measurable customer satisfaction.

Following table shows our current capabilities as of JAN, 1st, 2013 and future plans for 2014 and 2015.

No.	Manufacturing Capabilities	2013	2014	2015
1	Drilling Aspect Ratio	10:1	12:1	15:1
2	Minimum Drill Size	.006	.006	.005
3	Minimum Inner Layer Pad Size	.016	.014	.014
4	Minimum Outer Layer Pad Size	.016	.014	.014
5	Minimum Anti-Pad on Power/Ground Planes	.016	.014	.014
6	Minimum Buried/Blind Via Pad Size	.016	.014	.014
7	Minimum Buried/Blind Via Hole Size	.008	.006	.006
8	Minimum Inner Layer Line Width	.003	.003	.003
9	Minimum Outer Layer Line Width	.003	.003	.003
10	Minimum Inner Layer Spacing	.003	.003	.003
11	Minimum Outer Layer Spacing	.003	.003	.003
12	Maximum Overall Board Thickness	.250	.250	.250
13	Minimum Dielectric Thickness	.003	.0025	.002
14	Minimum Component Pitch-Plating and Testing	.006	.006	.006
15	Layer to Layer Registration Tolerance	.004	.004	.003
16	Conductor to Board Edge	.007	.006	.005
17	Solder Mask Clearance	.003	.003	.002
18	Solder Mask Dam between SMT Pads	.004	.003	.002
19	Minimum Base Copper Weight in oz.	.5	.5	.25
20	Maximum Overall Copper thickness	5	6	8
21	Maximum Layer Count	40	42	44
22	Plated Hole Tolerance	±.002	±.002	±.002
23	Maximum PCB Dimensions	19x25	19x25	19x25
24	Impedance Tolerance	±8%	±7.5%	±5%
26	Equipment Purchase Plan	Automated MLB Press – Year 3Q, 2013 Horizontal Black Oxide- Year 4Q, 2013 Laser Drill – Year 1Q, 2014 Plasma Etch System - Year 2Q,2014 Direct Imaging – Year 3Q, 2014		